

## AMENDMENTS TO CLAIMS

Claims 1-9 (canceled)

10. (currently amended) ~~The method according to claim 9, wherein~~ A method of manufacturing an electronic component comprising a contact having a terminal section for brazing and a contact section, said method comprising the steps of:

~~the step of constructing the~~ a base member of said contact made of a material which is poorly wettable to a weld brazing material ~~further includes by~~ forming a primer plating layer made of a material which is poorly wettable to said weld brazing material on said base member;

~~the step of forming the~~ on said base member a finish plating layer made of a material which is highly wettable to the weld brazing material ~~is carried out to form the finish plating layer on the~~ ~~thus formed~~ primer plating layer, and

~~the step of forming the~~ an exposed region of said poorly wettable base member by selectively removing a portion of said highly wettable finish plating layer by means of a mechanical processing technique ~~is carried out to selectively remove both a portion of said primer plating layer and a portion of said finish plating layer by a mechanical processing technique, said exposed region of said poorly wettable base member serving as an arresting region for arresting creeping-up of said weld brazing material.~~

Claim 11. (canceled)

12. (original claim) The method according to claim 10, wherein

said base member is made of copper alloy, and

said finish plating layer is made of any one of gold plating layer, tin or tin alloy plating layer, and lead or lead alloy plating layer.

13. (original claim) The method according to claim 10, wherein said primer plating layer is made of nickel alloy plating layer.

Claim 14. (canceled)

15. (previously added) The method according to claim 10, wherein said mechanical processing technique is any of mechanical cutting or grinding technique, electric discharge machining technique, electron-beam machining technique and laser beam machining technique.

Claim 16. (canceled)

17. (previously added) The method according to claim 12, wherein said mechanical processing technique is any of mechanical cutting or grinding technique, electric discharge machining technique, electron-beam machining technique and laser beam machining technique.

18. (previously added) The method according to claim 13, wherein said mechanical processing technique is any of mechanical cutting or grinding technique, electric discharge machining technique, electron-beam machining technique and laser beam machining technique.

19. (currently amended) ~~The method according to claim 9, wherein~~ A method of manufacturing an electronic component comprising a contact having a terminal section for brazing and a contact section, said method comprising the steps of:

~~the step of constructing the~~ a base member of said contact made of a material which is poorly wettable to a weld brazing material ~~further includes by~~ forming a primer plating layer made of a material which is poorly wettable to said weld brazing material on said base member, whereby said primer plating layer serves as a surface layer of the base member;

~~the step of forming the~~ on said base member a finish plating layer made of a material which is highly wettable to the weld brazing material ~~is carried out to form the finish plating layer on said primer plating layer, and~~

~~the step of forming the~~ an exposed region of said poorly wettable base member by selectively removing a portion of said highly wettable finish plating layer by means of a mechanical processing technique ~~is carried out to selectively remove a portion of said finish plating layer by a mechanical processing technique to obtain the exposed region of the primer plating layer serving as the arresting region.~~

20. (previously added) The method according to claim 19, wherein said mechanical processing technique is a laser beam machining technique.

21. (previously added) The method according to claim 19, wherein:

the step of forming the finish plating layer is carried out to form a first finish plating layer on said primer plating layer at the terminal section and a second finish plating layer integrally contacted to the first finish plating layer on said primer plating layer at the contact section, and

the step of forming the exposed region is carried out to selectively remove a portion of said first and/or second finish plating layer by a mechanical processing technique.

22. (previously added) The method according to claim 21, wherein said mechanical processing technique is a laser beam machining technique.

23. (previously added) The method according to claim 10, wherein

the step of forming the finish plating layer is carried out to form a first finish plating layer on said primer plating layer at the terminal section and a second finish plating layer integrally contacted to the first finish plating layer on said primer plating layer at the contact section, and

the step of forming the exposed region is carried out to selectively remove a portion of said first and/or second finish plating layer and a portion of said primer plating layer by a mechanical processing technique.

24. (previously added) The method according to claim 23, wherein said mechanical processing technique is a laser beam machining technique.